

# **Accelerated Testing**

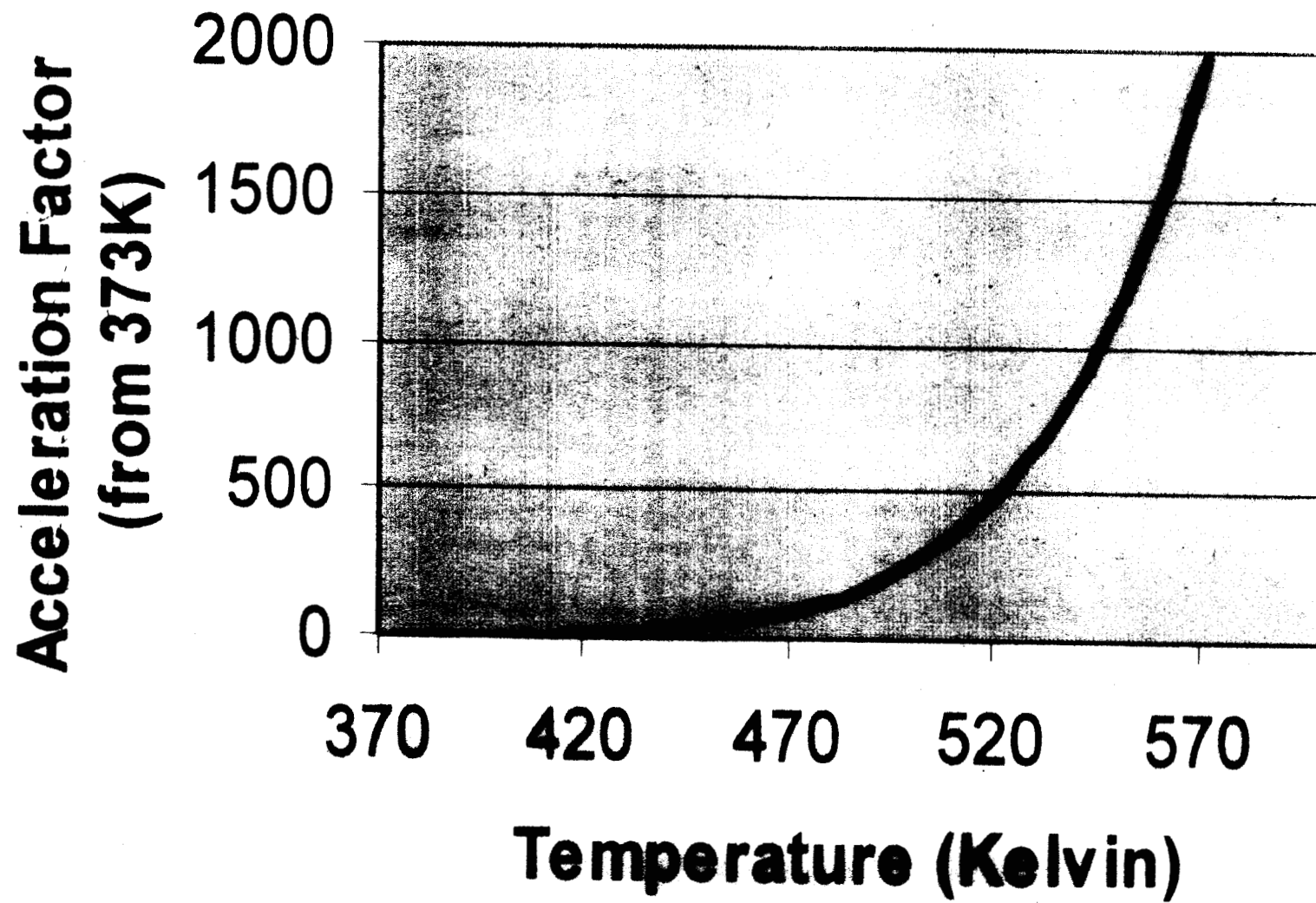
## **Requirement for a Valid Test**

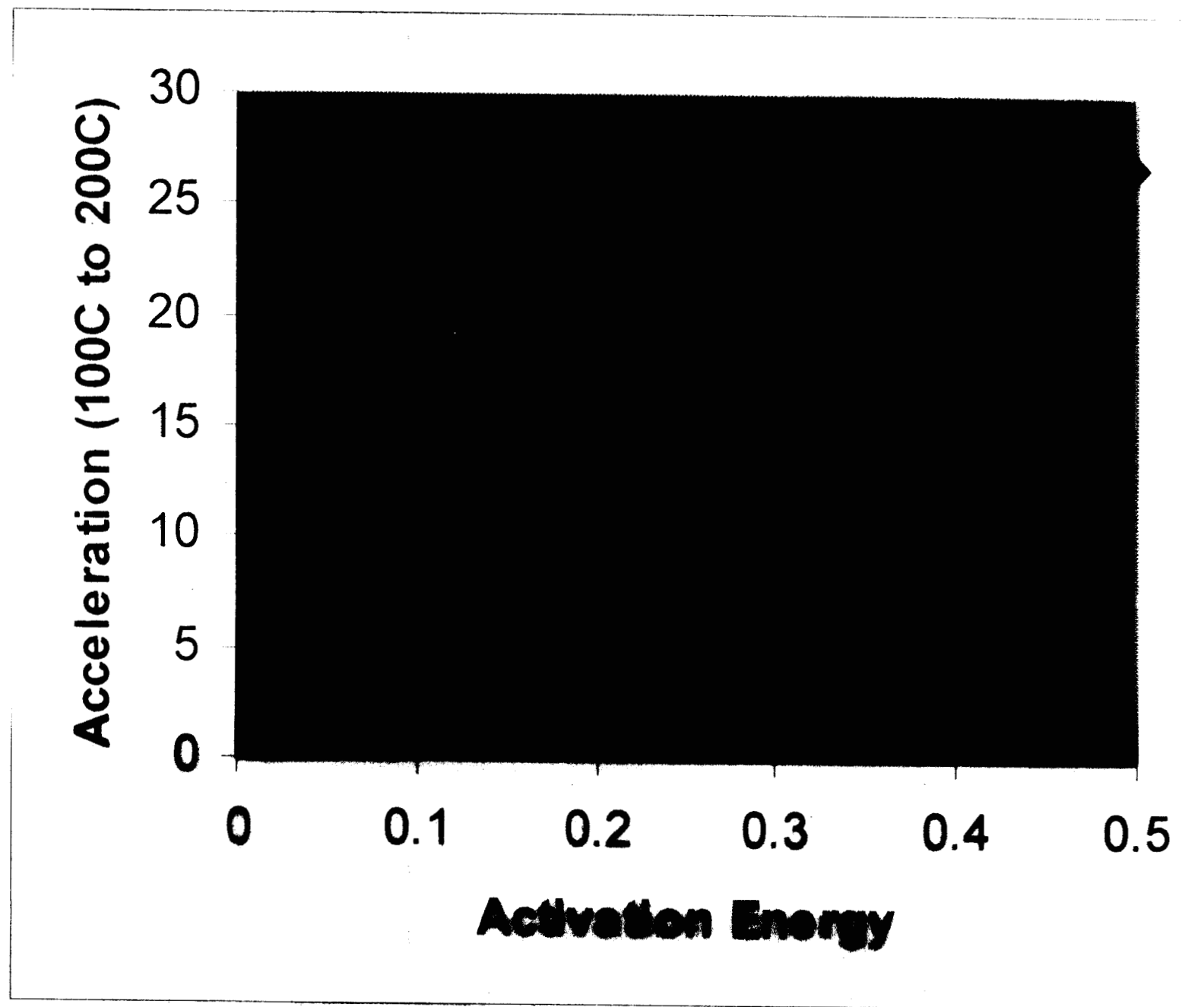
**Must exercise same failure mechanisms as  
those found under operational conditions**

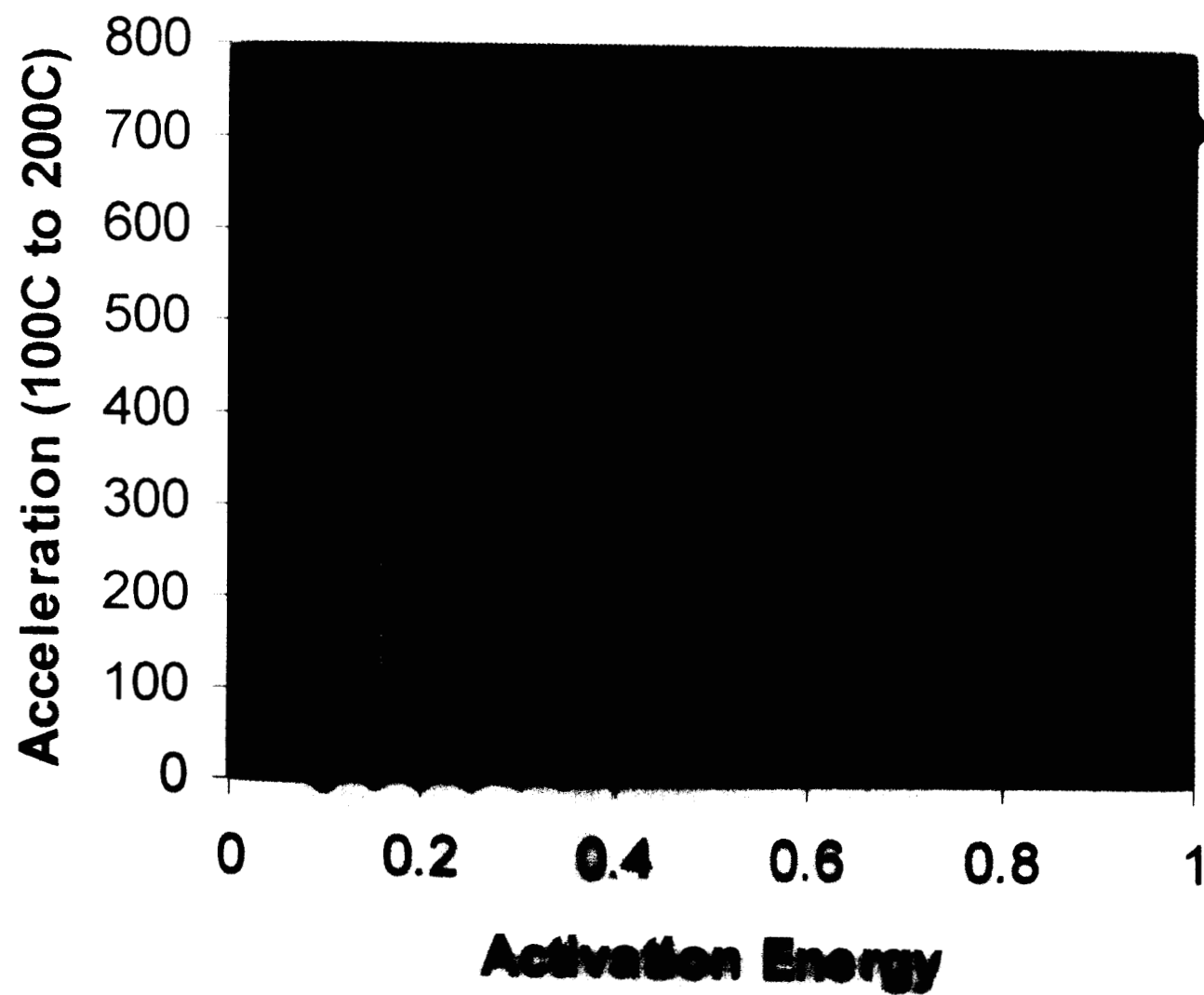
**NO EXCEPTIONS!!!**

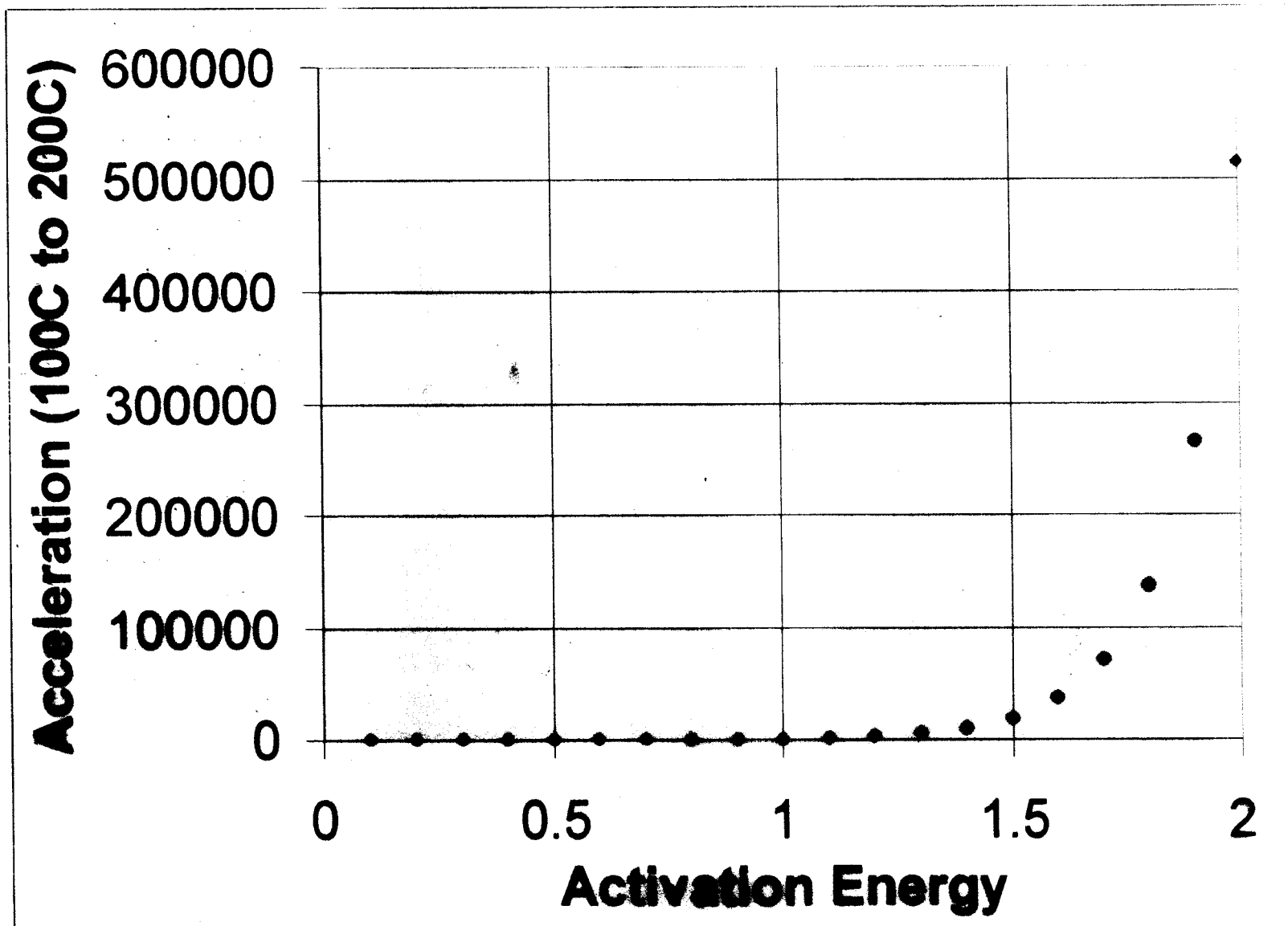
# Extrapolation

- **Failure Model**
  - **Must be equally valid at stress and at use conditions**
- **Stress Conditions limited by physics of the failure process**
  - **Overstressing**









# Arrhenius

- Most actual failure mechanisms are not purely Arrhenius
  - Often complex with other temperature dependencies besides thermal activation
- Most, however, do have an Arrhenius component
  - Usually associated with a mass transport mechanism

# Extrapolation

$$Rate = A \exp\left(\frac{-\Delta H}{kT}\right)$$

- Arrhenius Relation
- **Thermally Activated**
- $\Delta H$  is the activation energy
  - Depends on **the** Failure Mechanism
  - Usually the Transport Mechanism (**Diffusion**)

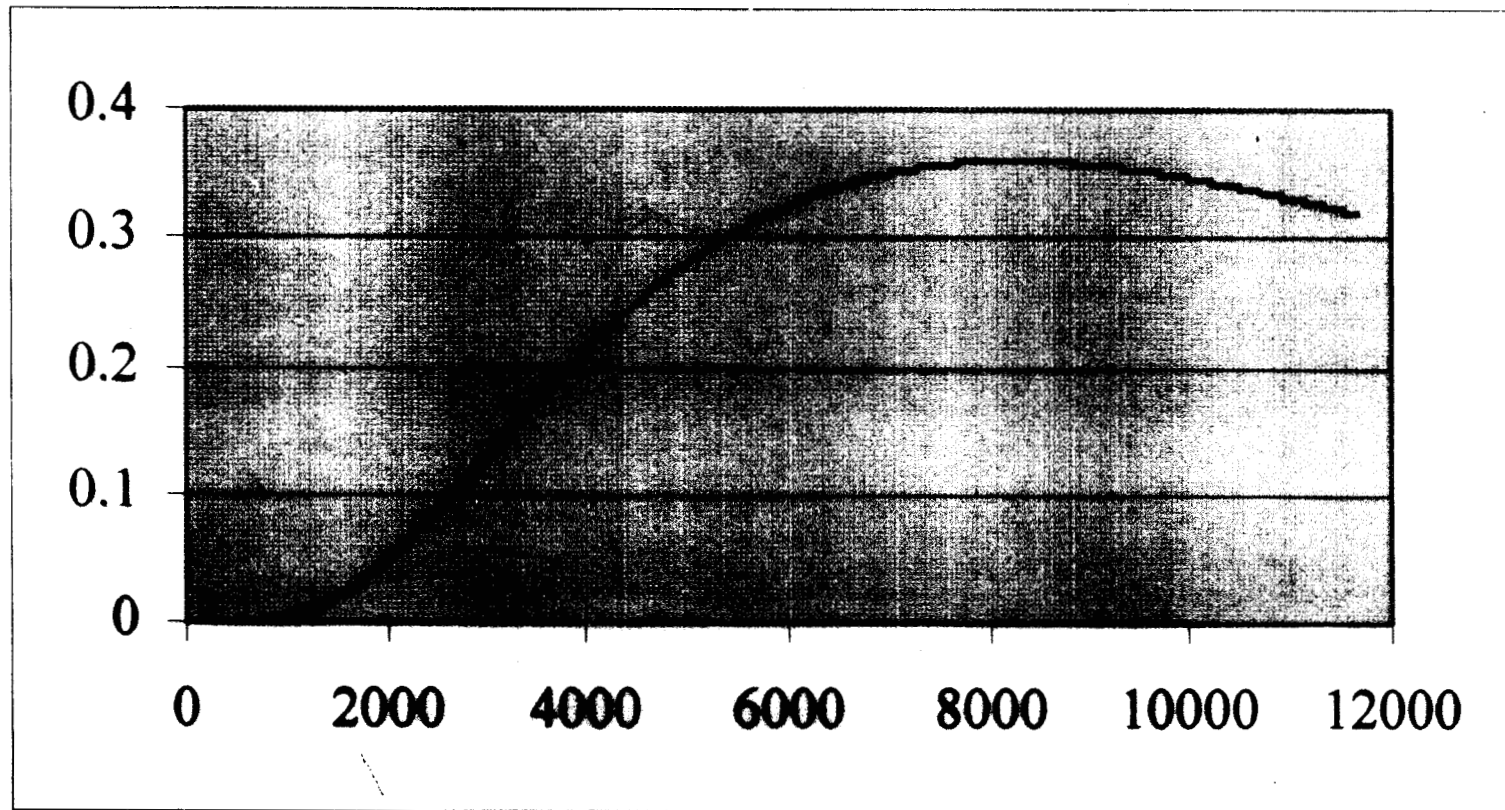


# **Extrapolation**

## **Acceleration Factor**

- **Relates** time at stress to time in the field
- **Depends** on Failure Mechanism
- **Requires** Failure Model
  - Electromigration
  - Stress Voiding
  - Hot Carrier Degradation
  - TDDB
  - Corrosion

# Bathtub Curve Experimental



Corollary

*Everything is Wearout*

*Defects **make** the Difference*

# Accelerated Testing

- **Implicit in the concept of accelerated testing is the assumption that there is a valid physical model that relates failure at the accelerated test conditions to operational use conditions**
- **Empirical Models are dangerous and cannot be recommended**
  - **Only good for interpolation not extrapolation**

# Extrapolation

- Use Conditions (Typical)
  - Temperature
    - 50 to 125C
  - Voltages
    - 5 Volts to 1.5 Volts
  - Current Density
    - Up to  $5 \times 10^5$  Amps/cm<sup>2</sup>

# Extrapolation

- **Acceleration**
  - **Reduce failure times to experimentally convenient levels.**
    - Hours as opposed to years
  - **Accomplished by operating outside of typical use parameters**
    - **Depends on failure mechanism**

# Kendall and Stuart

## *The Advanced Theory of Statistics*

*“A statistical relationship, however strong and however suggestive, can never establish a causal connection. Our ideas on causation must come from outside statistics, ultimately from some theory”*

# Max Born

*“The concept of chance enters into the very first steps of scientific activity, by virtue of the fact that no observation is absolutely correct.....whether a concrete case of a cause-effect relationship exists can only be judged by applying the laws of chance to the observation”*



# Why Accelerated Testing?

- Product lifetime in years
  - 100,000 hours at 85C
  - 10 Years at 100C
  - 5 years at 125C
- Development time in months
  - 18 to 24 months **typical time** to market for **microprocessor**

# Challenges

- **Extrapolation**
  - Obtain Data in a short time (weeks)
  - Extrapolated to 10 years or more in lifetime
- **Scaling**
  - **Test** structure is small and simple
  - **Product** chip is large and complicated

# Reliability

- **Through Qualification**
  - **Qualification Testing**
    - **Lifetime Predictions**
    - **Qualification Criteria**
  - **Design Verification**
    - **Designers**
    - **Product Engineers**
  - **Reproducibility**
    - **Yield**
    - **Process Engineering**

# Reliability

- **Through Generation of Design Rules**
  - **Reliability Testing**
  - **Process Engineering**
    - **Yield**
    - **Capability**
  - **Marketing Requirements**
    - **Performance**
    - **Reliability**

# Failure Mechanisms

- **Electromigration**
  - Temperature, Current Density
- **Stress Voiding**
  - Temperature
- **Hot Carrier, TDDB**
  - Temperature, Voltage, Frequency
- **Corrosion**
  - Temperature, Humidity, Cycling
- **Thermal Fatigue, Soret Effect**
  - $\Delta T$ , Cycle Frequency

# Modes vs. Mechanisms

- If we can test failure mechanisms and understand the relationship, we do not need to reproduce the failure mode.
- Requires detailed understanding of the failure process and materials science

# Reliability

- **Failure Mechanism**
  - **The physical process that leads to failure**
    - Electromigration
    - TDDB
    - Hot Carrier Degradation
    - Corrosion
    - Thermal Fatigue
    - Alpha Particle
    - ESD

# Reliability

- **Failure Mode**
  - How the failure manifests itself
    - **Functional Failures**
    - **Speed Shifts**
    - **Doesn't conduct electricity**
      - **Open Circuit**
    - **Conducts too much electricity**
      - short circuit
      - leakage
  - **Errors**



# Definitions and Distinctions

- MTF
  - Light bulbs will fail after approximately 1000 hours
  - Throw it away
- MTBF
  - The average lamp will fail after 1000 hours
  - Many light bulbs of various ages
  - replace the light bulb

# MTF and MTBF

- MTF is NOT a function of time
  - Characteristic of the failure distribution
  - MTF IS a time
- MTBF can be a function of time.
  - For a system composed of identical parts with a defined MTF, the MTBF will decrease as a function of time

# Definitions and Distinctions

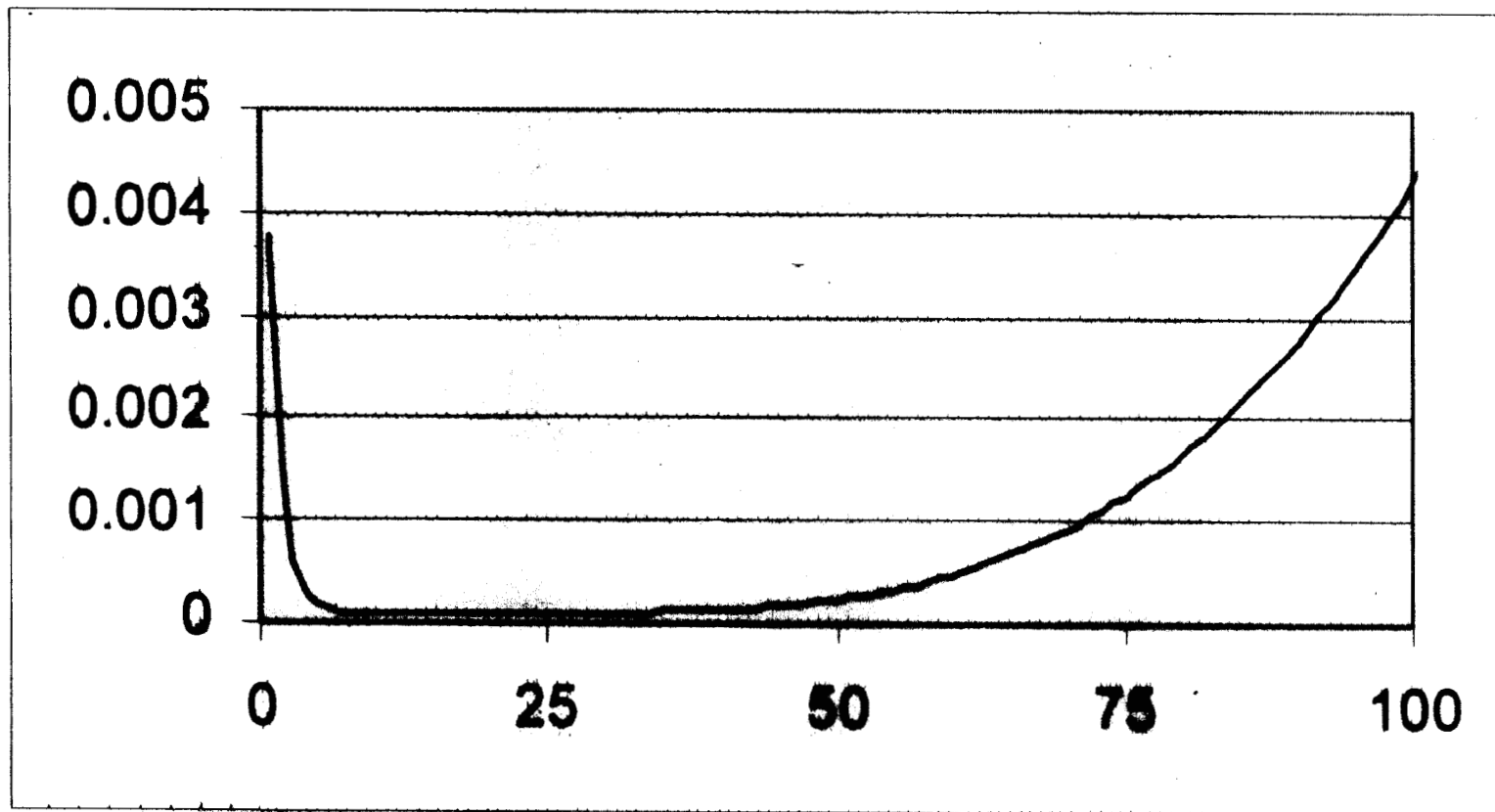
- **MTF**
  - **Median Time to Failure**
    - **Component Failure**
    - **Non-Repairable**
    - **Wear-out**
- **MTBF**
  - **Mean Time Between Failures**
    - **Repairable Systems**
    - **Maintenance Schedule**

# Definitions and Distinctions

- FITs
  - “Failures In Time”
- Failures in  $10^9$  device hours
  - can be misleading
  - must be used properly

1 million devices for 10 hours does NOT equal  
10 devices for 1 million hours

# Bathtub Curve



# Reliability

- Reliability requires the input of more than just the reliability engineer
  - Design
  - Reliability Testing
  - Manufacturing
  - Process Engineering
  - Product Engineering
  - Yield Engineering
  - Marketing

# Reliability

- Definition

- Definitions and Standards Committee of the IEEE

- “The ability of an item to perform a required function under stated conditions for a stated period of time”*

# Reliability

- James R. Schlesinger
  - Former US Secretary of Defense

*“Reliability is, after all, engineering in its most practical form”*